

## **REMARKS**

By the above amendments, a number of amendment have been made to the claimed subject matter so as to present a preferred scope of coverage.

Attached hereto is a marked-up version of the changes made to the claims by the current Preliminary Amendment. The attached page is captioned "Version with Markings to Show Changes Made".

An early and favorable action on the merits is respectfully requested.

Respectfully submitted,

Yutaka WADA et al.

Nils E. Pedersen

Registration No. 33,145 Attorney for Applicants

NEP/krl Washington, D.C. 20006-1021 Telephone (202) 721-8200 Facsimile (202) 721-8250 April 11, 2002

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## <u>Version with Markings to</u> <u>Show Changes Made</u>

## CLAIMS

1. A method for polishing an object having raised and depressed pattern thereon to produce a flat and mirror had the thick to have been polished surfaced by using an abrading plate, said method plate. comprising:

polishing said object by supplying a liquid not containing any abrasive particles for a determined time period; and

further polishing said object by supplying abrasive particles so as to perform additional removal of a surface material to uniformly remove a specific film thickness.

2. A method according to claim 1, wherein said additional removal of a surface material is performed with said abrading plate by supplying a liquid not containing any abrasive particles for a specific duration, followed by additional polishing by supplying a slurry containing abrasive particles to said surface to be polished.

3. A method according to claim 1, wherein said additional removal of a surface material is performed by:

polishing using an abrading plate and supplying a liquid not containing any abrasive particles for a specific time duration, and

additional polishing while concurrently dressing said abrading plate with a liquid not containing abrasive

APR. 11. 2002 3:50PM WENDEROTH LIND & PON NO. 532

particles thereby to generate free abrasive particles therefrom.

A method according to claim 1, wherein said additional removal of a surface material is performed by:

polishing using an abrading plate and supplying a liquid not containing any abrasive particles for a specific time duration, and

additional polishing using a polishing cloth and a slurry containing abrasive particles. 10

A polishing apparatus for polishing a surface of a substrate hobject having fine raised and depressed structures thereon by pressing said surface to an abrading 15 surface of an abrading plate, said apparatus comprising:

a holder for holding said substrate object;

an abrading plate holder for holding said abrading plate; surface Complising abrasine particles and a limited a mechanism for pressing said surface of said

- 20 Substrate object to said abrading surface of said abrading plate while producing a sliding motion over a polishing interface;
  - device for supplying a liquid not containing abrasive particles to said polishing interface; and
  - a surface material removal device for performing additional material removal by supplying abrasive particles, 25 said device integrally mounted in said polishing apparatus.

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- An apparatus according to claim 5, wherein said 6. surface material removal device is a device for supplying a slurry containing abrasive particles to said polishing interface.
- An apparatus according to claim 5, wherein said surface material removal device is a device for dressing said surface of said abrading plate so as to produce / lelane I horn daid abrading an face abrasive particles.
- An apparatus according to claim 5, wherein said apparatus is provided with a first polishing means to perform polishing while supplying a liquid not containing abrasive particles to said polishing interface; and a second polishing means to perform polishing while supplying a slurry containing abrasive particles to said polishing 15 interface.
- 9. A method for polishing a surface of a workpiece, comprising: 20

first polishing the surface of the workpiece with an abrasive surface comprising abrasive particles and a binder binding said abrasive particles in the presence of a liquid; and

finish polishing the surface of the workpiece with a 25 polishing surface that comprises a buffing pad in the presence of a slurry.